CUI DEVICES

MODEL: HSS-B20-043H-01 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- solder pins for secure PCB mounting
- black anodized finish

RoHS

MODEL

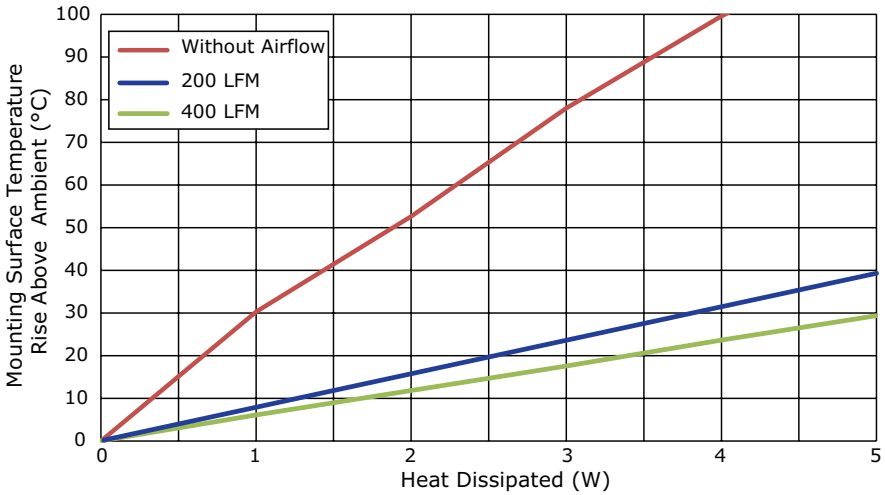
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSS-B20-043H-01	26.13	30.28	8.18	6.09	2.87

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	30.28	8.18	6.09
2	52.63	15.67	11.80
3	78.03	23.66	17.53
4	99.60	31.62	23.64
5	117.50	39.31	29.36

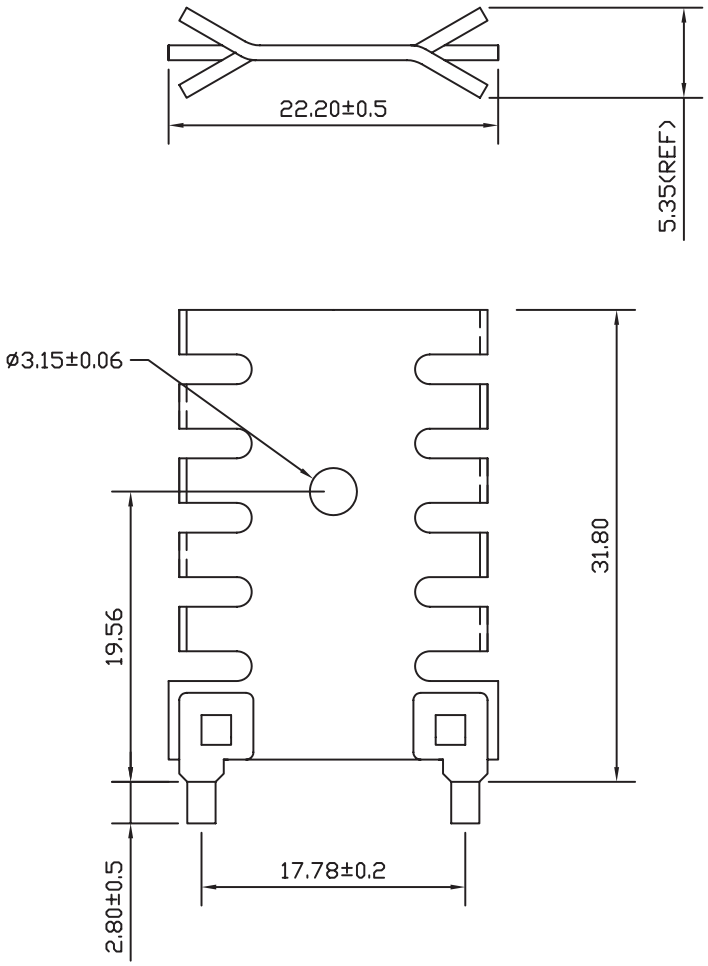
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL1100
FINISH	black anodized
THICKNESS	1.0 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	1.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/31/2017
1.01	brand update	02/12/2020

The revision history provided is for informational purposes only and is believed to be accurate.